

HT2812 Single Sound Generator

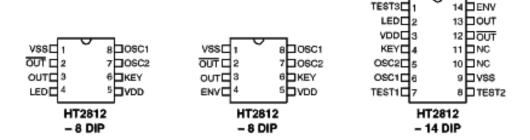
Features

- Single power supply: 2.4V~3.3V
- Low standby current at 3V, 1µA (Typ.)
- Auto power-off function
- Speaker or direct piezo application
- Built-in envelope control circuit
- 1Hz~8Hz programmable LED flash output
- Minimum external components

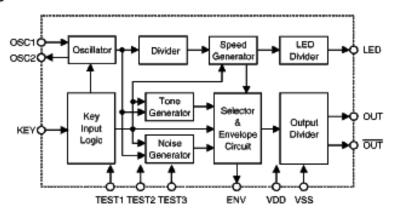
General Description

The HT2812 is a CMOS LSI chip designed for use in sound effect products. It is equipped with tone circuit, noise circuit, and other control logic to generate different sounds including rifle gun, machine gun, booming sound, door bell, alarm etc. The customer supplied sound source can be analyzed and programmed into an internal ROM by changing a mask layer during device fabrication. The HT2812 is suitable for various toy applications.

Pin Assignment



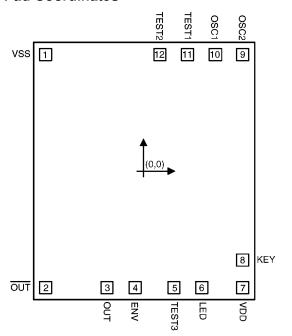
Block Diagram



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Pad Coordinates Unit: mil



Pad No.	X	Y
1	-27.127	32.3
2	-27.127	-32.3
3	-10.127	-32.3
4	-2.307	-32.3
5	8.488	-32.3
6	16.138	-32.3
7	27.528	-32.3
8	27.528	-24.65
9	27.528	32.3
10	19.878	32.3
11	12.228	32.3
12	4.578	32.3

Chip size : $67 \times 72 \text{ (mil)}^2$

Absolute Maximum Ratings*

Supply Voltage0.3V to 5V	Storage Temperature $-50 ^{\circ}\mathrm{C}$ to $125 ^{\circ}\mathrm{C}$
Input VoltageVss-0.3 to Vpp+0.3V	Operating Temperature 0°C to 70°C

*Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damageto the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

^{*} The IC substrate should be connected to VDD in the PCB layout artwork.



Electrical Characteristics

(Ta=25°C)

Symbol	Parameter	Test Conditions		Min.	/TL	Max.	Units
		V_{DD}	Conditions	wiln.	Тур.	MIGX.	Units
$ m V_{DD}$	Operating Voltage	3V		2.4	3	3.3	V
I_{STB}	Standby Current	3V	_	_	1	5	μА
${ m I}_{ m DD}$	Operating Current	3V	No load	_	300	600	μА
I_{OH}	Output Source Current	3V	$V_{\rm OH}$ =2.5 V	-1	-2	_	mA
$I_{ m OL}$	Output Sink Current	3V	$V_{\rm OL}$ =0.5 V	1	2	_	mA
I_{ENV}	ENV Source Current	3V	$V_{\rm OH}$ =2.5 V	-1	-2		mA
$I_{ m LED}$	LED Source Current	3V	$V_{OH}=2.5V$	-1	-2	_	mA
Fosc	Oscillator Frequency	_	$R=330k\Omega$	_	64	_	kHz
v_{IH}	"H" Input Voltage	3V	<u> </u>	2.4	_	_	V
$ m V_{IL}$	"L" Input Voltage	3V	<u> </u>	_	_	0.6	V

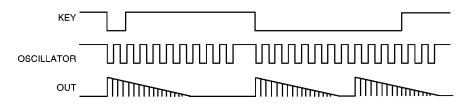
Pad Description

Pad No.	Pad Name	I/O	Description
1	VSS	_	Negative power supply, GND
2	OUT	О	Sound output pad, out of phase to pad 3
3	OUT	О	Sound output pad
4	ENV	0	Sound envelope control pad
5	TEST3	I	For IC test only
6	LED	0	LED flash output pad
7	VDD	_	Positive power supply
8	KEY	I	Key input pad, low active
9	OSC2	О	Oscillator output pad
10	OSC1	I	Oscillator input pad
11	TEST1	I	For IC test only
12	TEST2	I	For IC test only

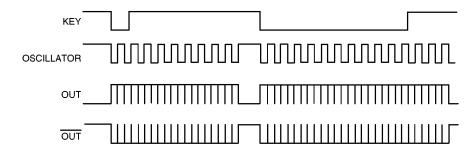


Timing Diagram

With an envelope



No envelope

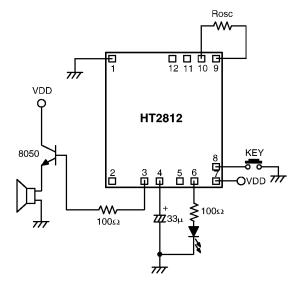


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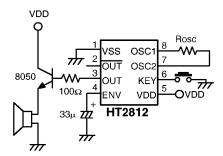


Application Circuits

Speaker output with an envelope

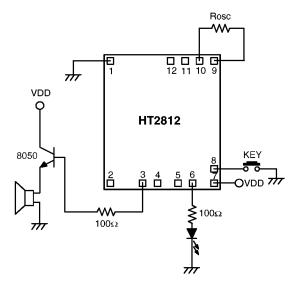


* The IC substrate should be connected to VDD in the PCB layout artwork.

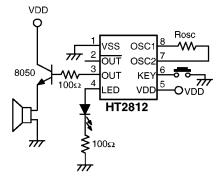




Speaker output without an envelope



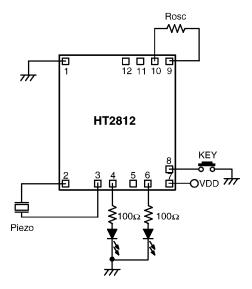
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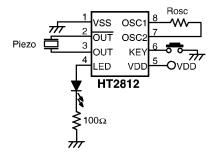
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Piezo output without an envelope

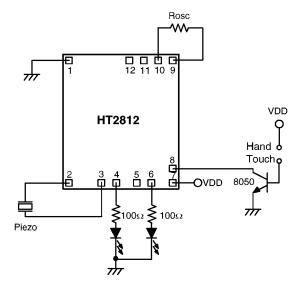


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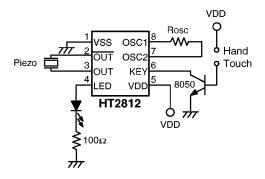




Hand touch trigger

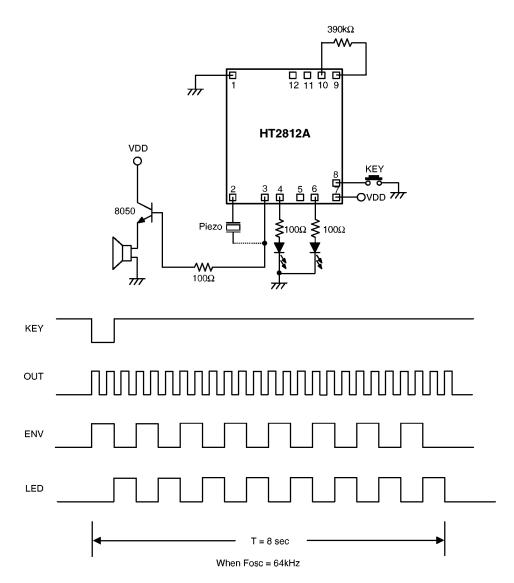


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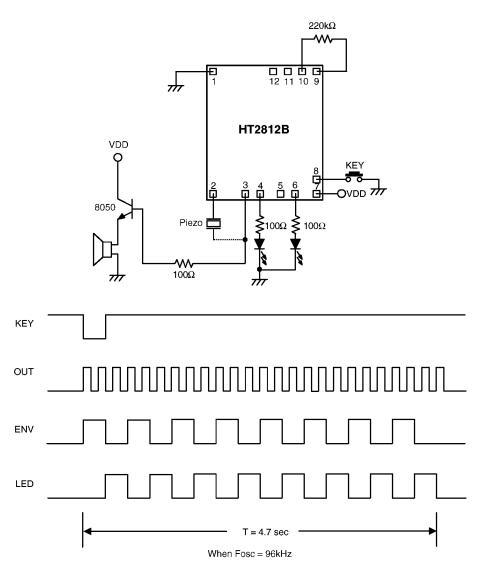
Application Circuit (HT2812A — Airplane)



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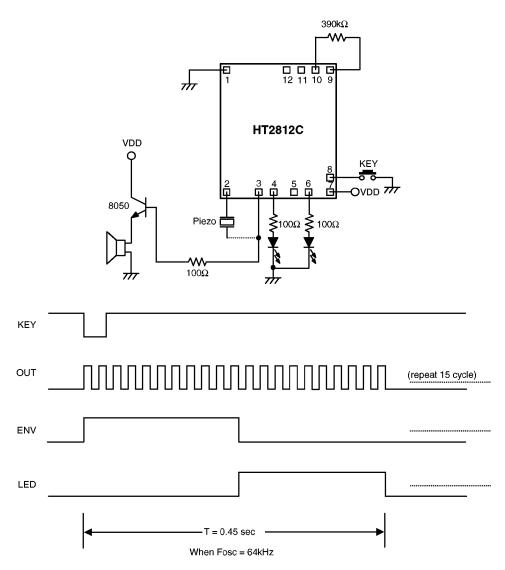
Application Circuit (HT2812B — Rocket)



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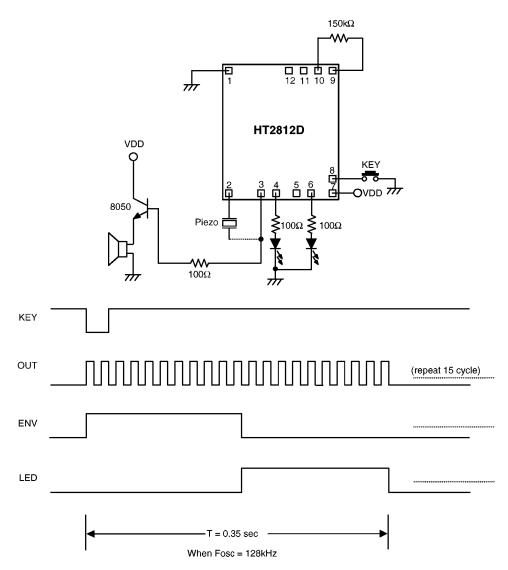
Application Circuit (HT2812C — Siren II)



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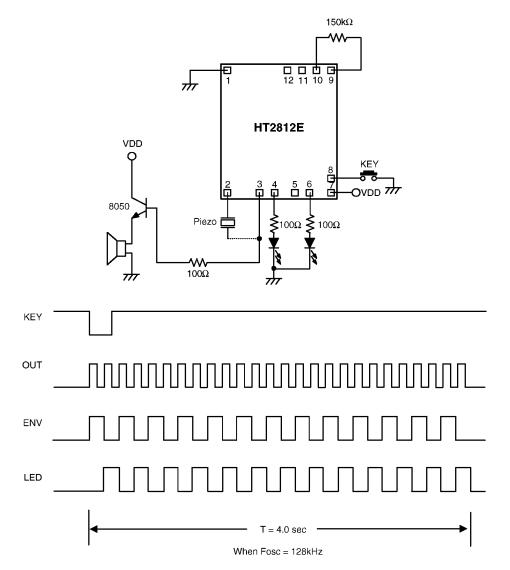
Application Circuit (HT2812D — Police Car)



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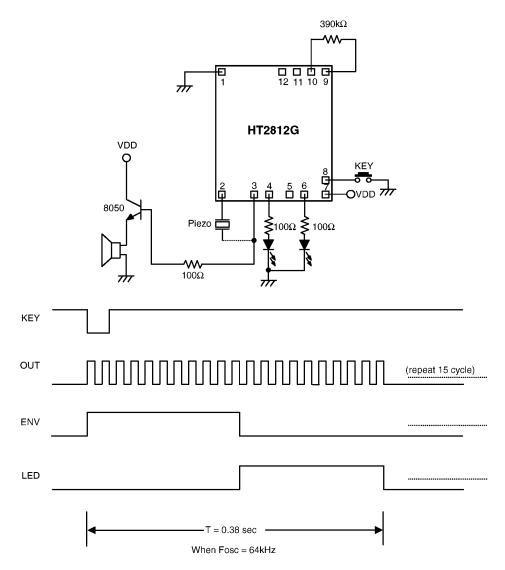
Application Circuit (HT2812E — Fire Brigade)



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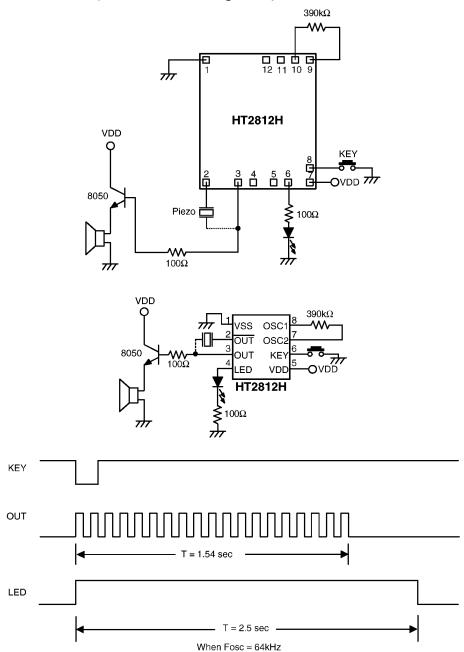
Application Circuit (HT2812F — Siren I)



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Application Circuit (HT2812H — Dialing Tone)

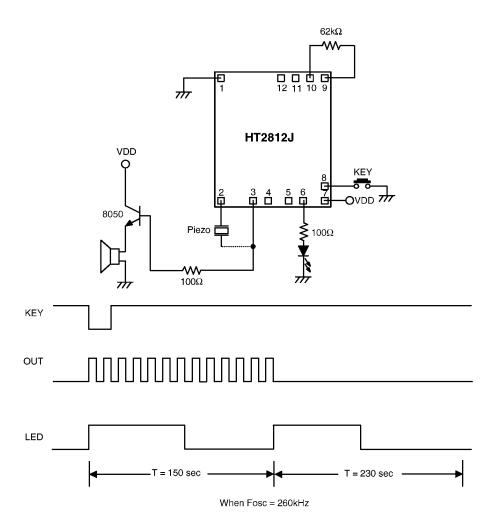


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15 10th July '97



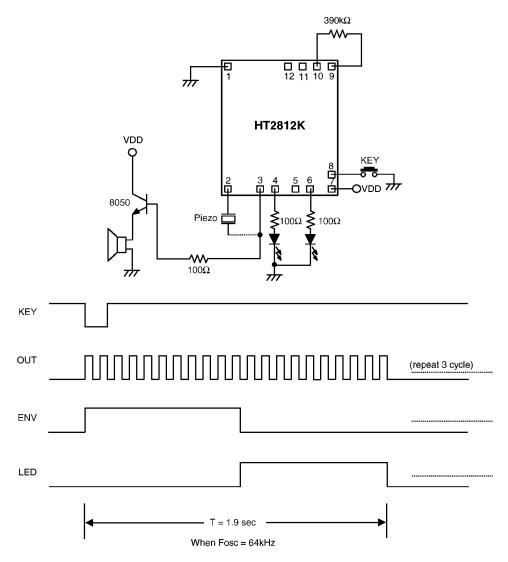
Application Circuit (HT2812J — Chicken Sound)



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Application Circuit (HT2812K — Ambulance Sound)



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